Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}	-	-	-	2.6	K/W
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm^2 cooling area[3]	-	-	40	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0V, I_D= -1mA	-40	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=-85µA	-2.0	-3.0	-4.0	
Zero gate voltage drain current	I_{DSS}	V_{DS}=-32V, V_{GS}=0V, T_j=25°C	-	-0.05	-1	µA
		V_{DS}=-32V, V_{GS}=0V, T_j=125°C[2]	-	-20	-200	
Gate-source leakage current	I_{GSS}	V_{GS}=-20V, V_{DS}=0V	-	-	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=-10V, I_D=-50A	-	9.2	12.6	mΩ

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0V, V_{DS}=-25V, f=1MHz	-	2820	3670	pF
Output capacitance	C_{oss}		-	1000	1500	
Reverse transfer capacitance	C_{rss}		-	30	60	
Turn-on delay time	$t_{d(on)}$	V_{DD}=-20V, V_{GS}=-10V, I_D=-50A, R_G=3.5Ω	-	17	-	ns
Rise time	t_r		-	10	-	
Turn-off delay time	$t_{d(off)}$		-	22	-	
Fall time	t_f		-	28	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=-32V, I_D=-50A, V_{GS}=0 to -10V	-	14	19	nC
Gate to drain charge	Q_{gd}		-	7	14	
Gate charge total	Q_g		-	39	51	
Gate plateau voltage	$V_{plateau}$		-	5.4	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25°C	-	-	-50	A
Diode pulse current[2]	$I_{S,pulse}$		-	-	-200	
Diode forward voltage	V_{SD}	V_{GS}=0V, I_F=-50A, T_j=25°C	-	-1	-1.3	V
Reverse recovery time[2]	t_{rr}	V_R=-20V, I_F=-50A, di_F/dt=-100A/µs	-	39	-	ns
Reverse recovery charge[2]	Q_{rr}		-	32	-	nC

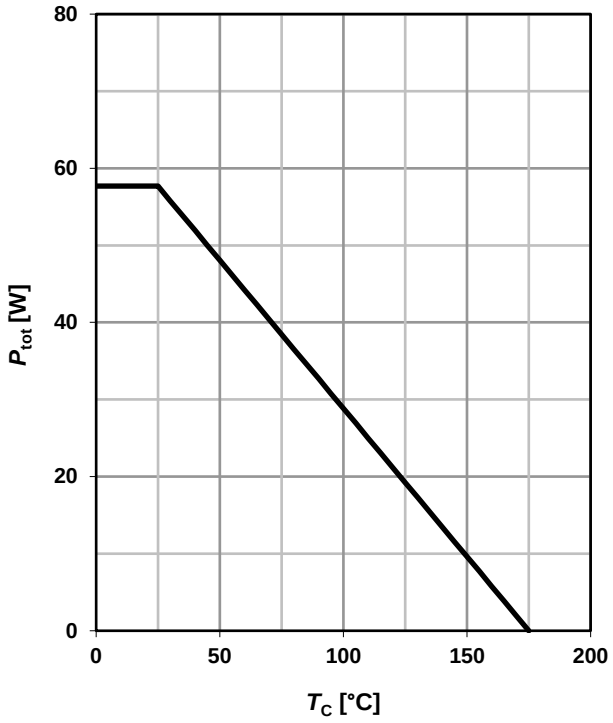
[1] Current is limited by bondwire; with an R_{thJC} = 2.6K/W the chip is able to carry -55A at 25°C.

[2] Defined by design. Not subject to production test.

[3] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

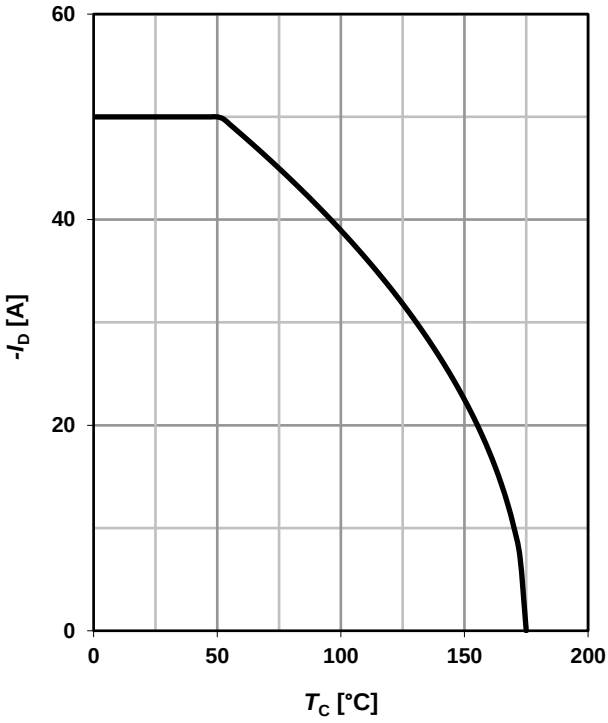
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} = -10V$



2 Drain current

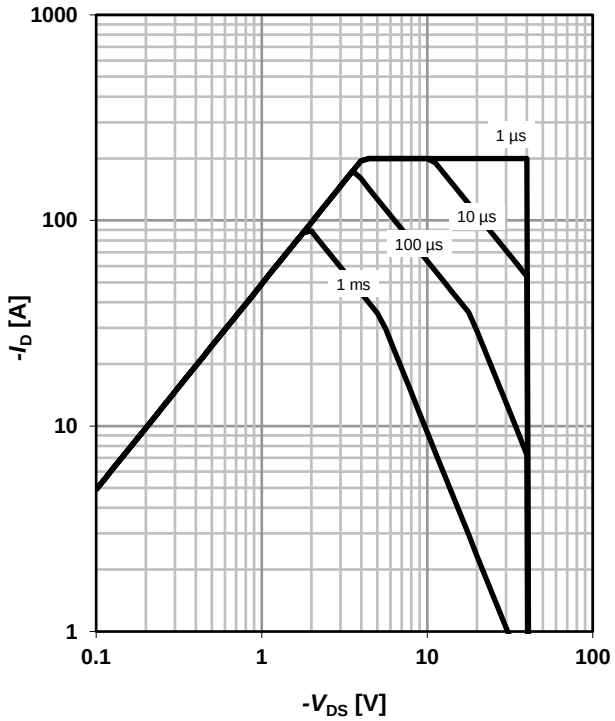
$I_D = f(T_C)$; $V_{GS} = -10V$



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

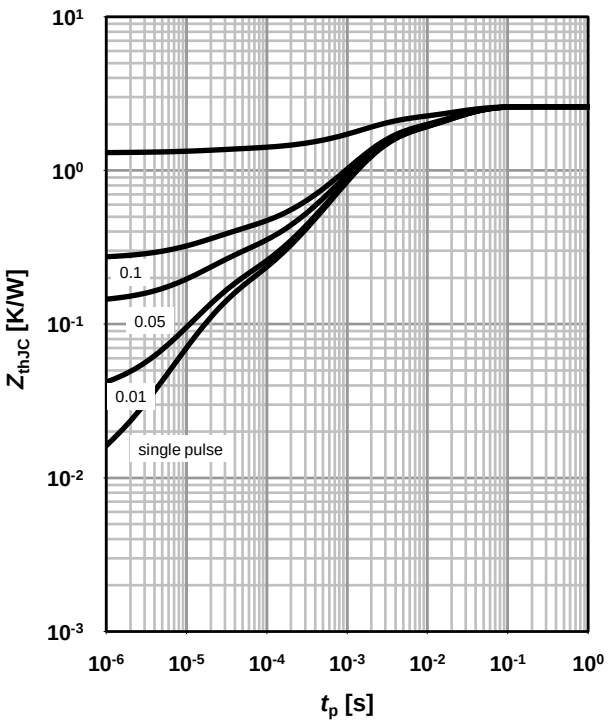
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

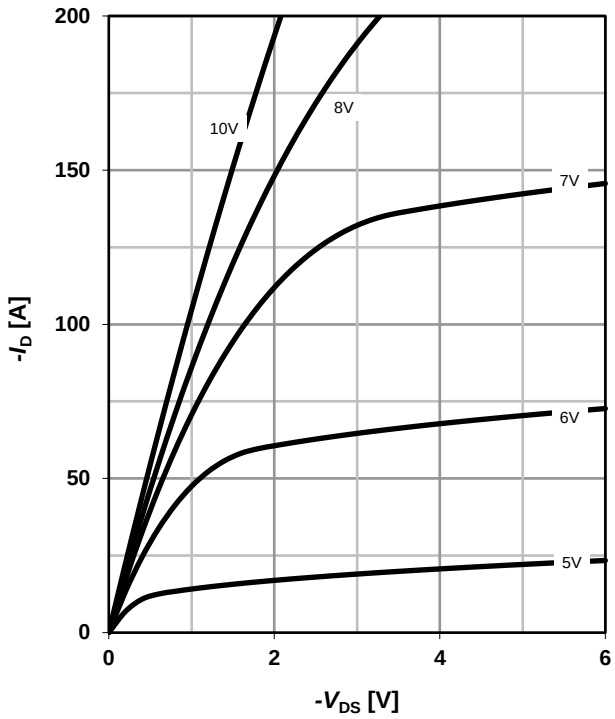
parameter: $D = t_p/T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

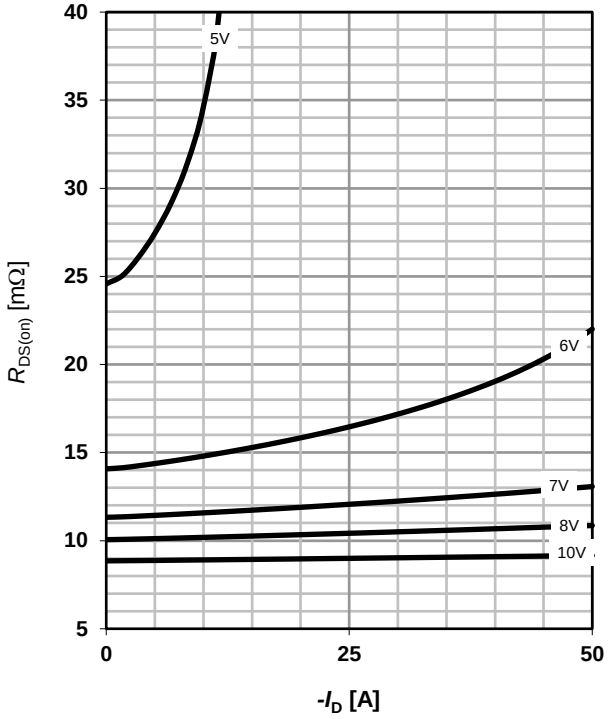
parameter: $-V_{GS}$



6 Typ. drain-source on-state resistance

$R_{DS(on)} = (I_D)$; $T_j = 25$ °C

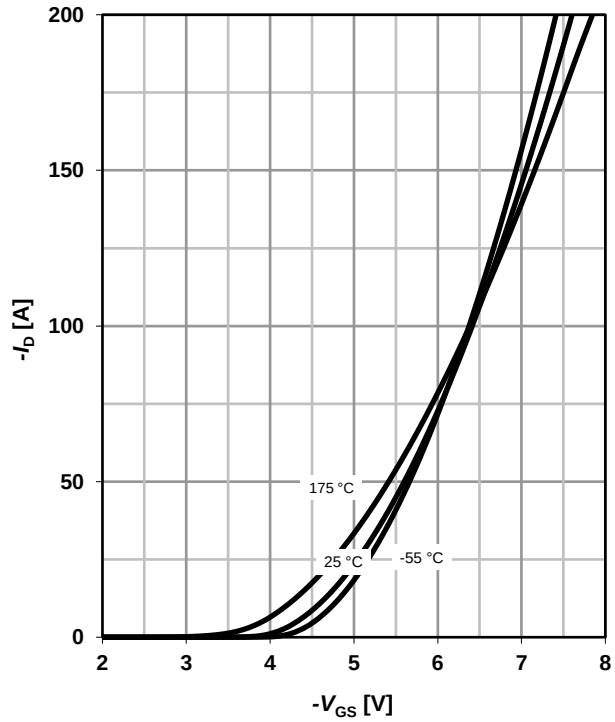
parameter: $-V_{GS}$



7 Typ. transfer characteristics

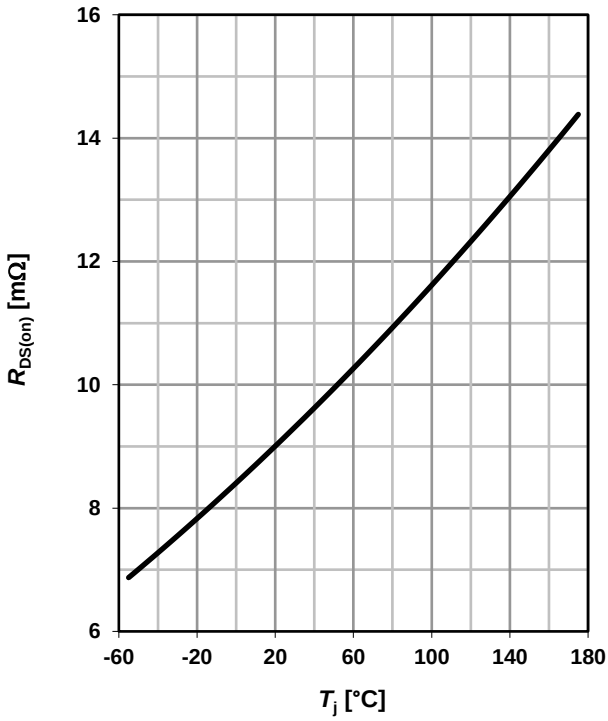
$I_D = f(V_{GS})$; $V_{DS} = -6$V

parameter: T_j



8 Typ. drain-source on-state resistance

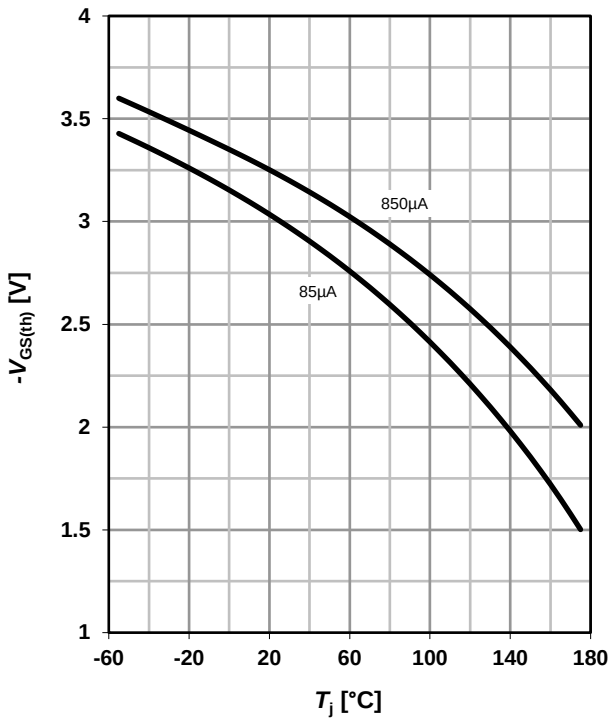
$R_{DS(on)} = f(T_j)$; $I_D = -50$ A; $V_{GS} = -10$ V



9 Typ. gate threshold voltage

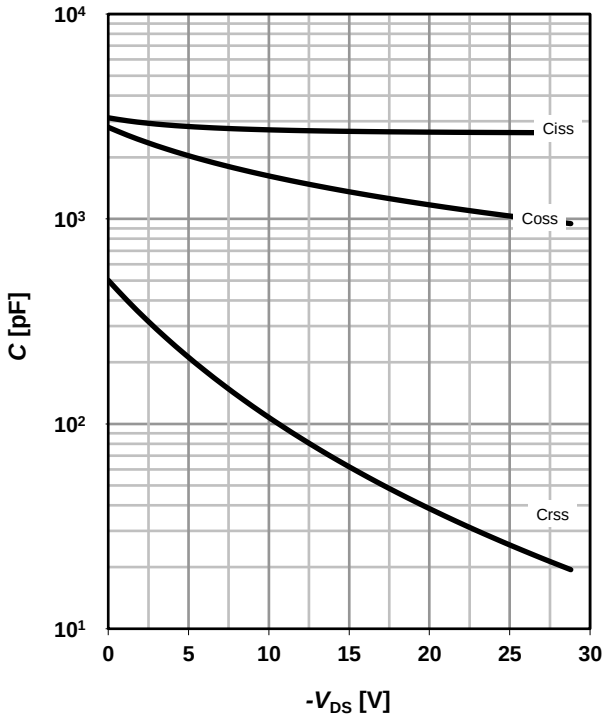
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: $-I_D$



10 Typ. capacitances

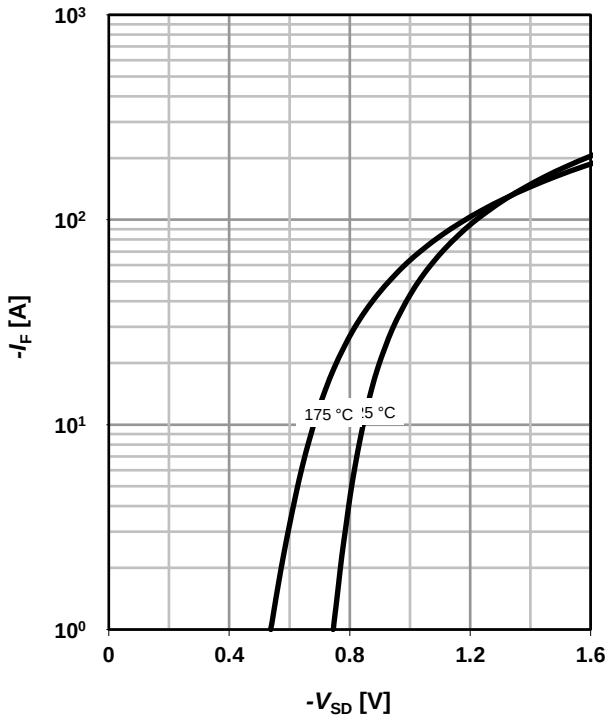
$C = f(V_{DS})$; $V_{GS} = 0$ V; f = 1 MHz



11 Typical forward diode characteristicis

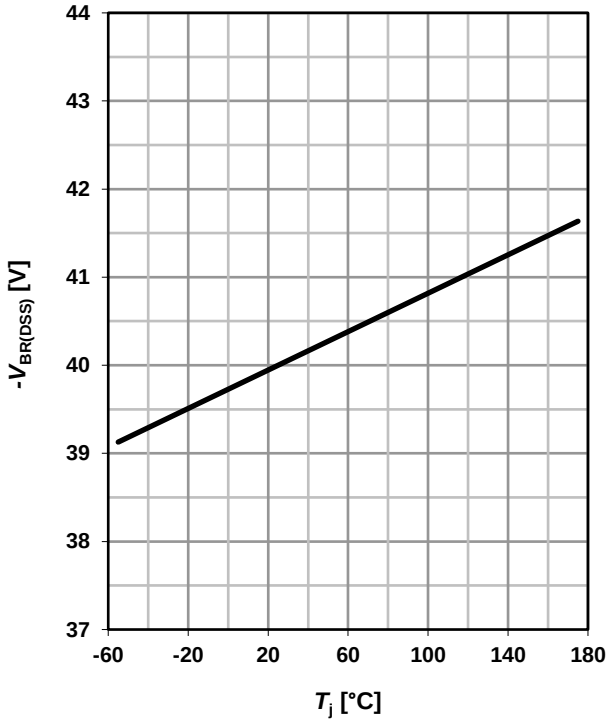
IF = f(V_{SD})

parameter: T_j



12 Drain-source breakdown voltage

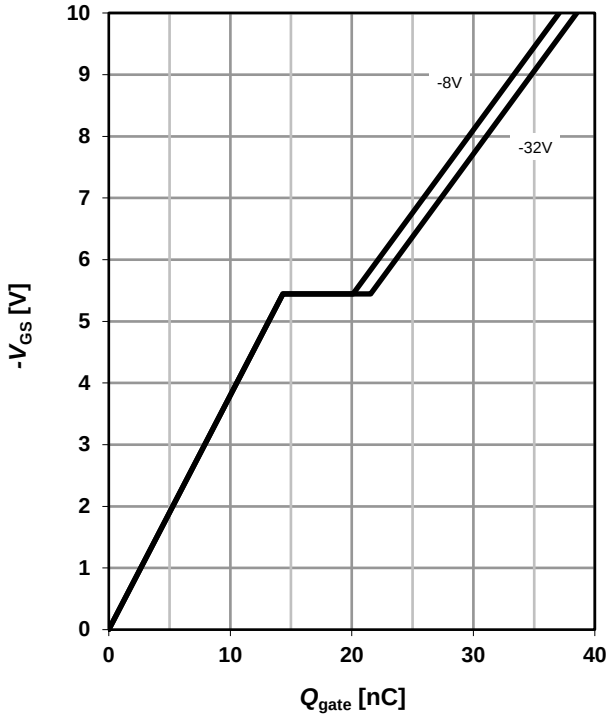
$V_{BR(DSS)} = f(T_j)$; I_D = -1 mA



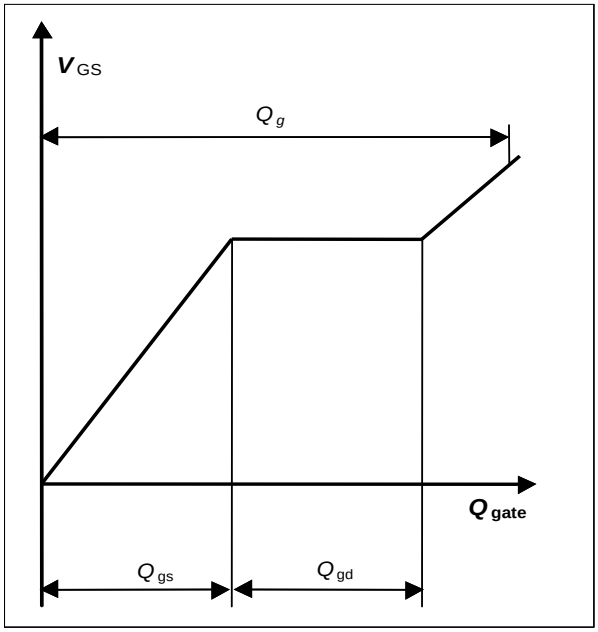
13 Typ. gate charge

$V_{GS} = f(Q_{gate})$; I_D = -50 A pulsed

parameter: V_{DD}



14 Gate charge waveforms



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Revision History

Version	Date	Changes
1.0	14.03.2011	Final Data Sheet
1.1	21.12.2012	Update of diagram 8
1.2	09.12.2013	Update of Idpuls and SOA
1.3	16.07.2019	graphs corrected